

REMARKS

Reconsideration and reversal of the rejections expressed in the Office Action of September 30, 2005 are respectfully contended in view of the following remarks and the application as amended. The present invention relates to an epoxy composition, comprising an uncured epoxy resin composition including a liquid epoxy resin and a non-sensitizing mercaptan composition capable of curing said epoxy resin when combined with said mercaptan composition to form a substantially uniform mixture, wherein said epoxy resin has a molecular weight greater than about 700.

Applicants affirm the election to prosecute the claims of Group I, claims 1-8 and 10-17 of the present application.

Claims 1-6, 8, 10-15 and 17 were rejected under 35 U.S.C. § 102(b) as being anticipated by Jorissen et al., U.S. Patent No. 5,548,026. Jorissen et al. relates to a two-part induction-curable epoxy adhesive comprising a first part of a polyfunctional epoxy, such as a sorbitol polyglycidyl ether, and a diepoxy compound such as a diepoxy bisphenol-A, wherein a portion of the diepoxy compound may preferably comprise a glycol-based epoxy having an epoxy equivalent weight of at least about 250. The second part of the adhesive is a curing agent, which preferably may be a mixture of -di(aminoalkyl)ether of diethylene glycol products, and a toughening agent. Note that the claims as amended overcome this rejection. Specifically, the Jorissen et al. reference neither discloses nor suggests an epoxy composition including a sorbitol based epoxy resin having a molecular weight (about 800-1000) as currently claimed, while still being liquid, as well as not being a contact sensitizer. Such enhanced aspects of the present invention as currently claimed are found at e.g., pages 4-6 of the present specification. Thus, this rejection is overcome.

Claims 1-3, 5, 7, 10-12, 14 and 16 were rejected under 35 U.S.C. § 102(b) as being anticipated by Japanese Patent No. 1-249828 (Japanese '828). Note that the claims as amended also overcome this rejection. Specifically, Japanese '828 neither discloses nor suggests an epoxy resin admixed with fillers and colorants selected from the group consisting of talc, titanium dioxide, carbon black and mixtures thereof; such an aspect was found in the now canceled claims 4 and 13, which are now incorporated into claim 1 as amended. Thus, this rejection is overcome as well.

Claims 4 and 13 were rejected under 35 U.S.C. §103(a) as being unpatentable over Japanese '828 as applied to the claims hereinabove, and further in view of Jorissen et al. The claims as amended overcome this rejection.

Claims 1-8 and 10-17 were rejected under 35 U.S.C. §103(a) as being unpatentable over Japanese Patent No. 2-108533, Miyamoto Publication No. 2004/0006944, Japanese Patent No. 61-138232, U.S. Patent No. 6,770,957 and Japanese Patent No. 61-185526, in view of Jorissen et al. As pointed out above, the Jorissen et al. reference neither discloses nor suggests an epoxy composition including a sorbitol based epoxy resin having a molecular weight (about 800-1000) as currently claimed, while still being liquid, as well as not being a contact sensitizer. Note that it is acknowledged in the Office Action that the claimed epoxy resin having a molecular weight of greater than about 700 is not recited in the other references cited in this paragraph. Thus, this rejection is overcome.

Claims 7 and 22 were rejected under 35 U.S.C. §103(a) as being unpatentable over Jorissen et al. as applied to the claims hereinabove, and further in view of Japanese '533 and Miyamoto. It is believed that this rejection is overcome based on the previous discussion. Furthermore, as there is no claim 22 in the present application, it is not clear which claim the Examiner refers to, in addition to claim 7.

For all of the above reasons, it is respectfully contended that the solicited claims define patentable subject matter. Reconsideration and reversal of the rejections expressed in the Office Action of September 30, 2005 are respectfully requested. The Examiner is invited to call the undersigned if any questions arise during the course of reconsideration of this matter.

Respectfully submitted,

Dated: 12/22/05

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